



## Product/Process Change Notice - PCN 23\_0287 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

<b>PCN Title:</b>	Notification of Qualification on SMT Paste, and Die Thickness Change for LT8648S
<b>Publication Date:</b>	06-Mar-2024
<b>Effectivity Date:</b>	08-Jun-2024 <i>(the earliest date that a customer could expect to receive changed material)</i>
<b>Revision Description:</b>	Initial Release

### Description Of Change:

- Change the passive component attached material from SnSb5 to SAC305.
- Die thickness updated from 450um to 200um.

### Reason For Change:

Improve the manufacturability and add substrate supplier.

### Impact of the change (positive or negative) on fit, form, function & reliability:

There is no change on fit, form, function, and reliability of the products.

### Product Identification *(this section will describe how to identify the changed material)*

Production shipment of the product incorporating the new material will begin no sooner than the effective date.

### Summary of Supporting Information:

The qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

### Supporting Documents

**Attachment 1: Type:** Qualification Results Summary

[ADI\\_PCN\\_23\\_0287\\_Rev\\_-\\_LT8648S\\_Reliability\\_Report.pdf...](#)

**Attachment 2: Type:** Delta Qualification Matrix

[ADI\\_PCN\\_23\\_0287\\_Rev\\_-\\_PCN-Delta-Qualification-Matrix-ZVEI-5\\_0\\_14\\_1.xls...](#)

**Attachment 3: Type:** Other

[ADI\\_PCN\\_23\\_0287\\_Rev\\_-\\_Thermal\\_analysis\\_summary\\_LT8648S\\_20240117.xlsx...](#)

Note: If applicable, the device material declaration will be updated due to material change.

### ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

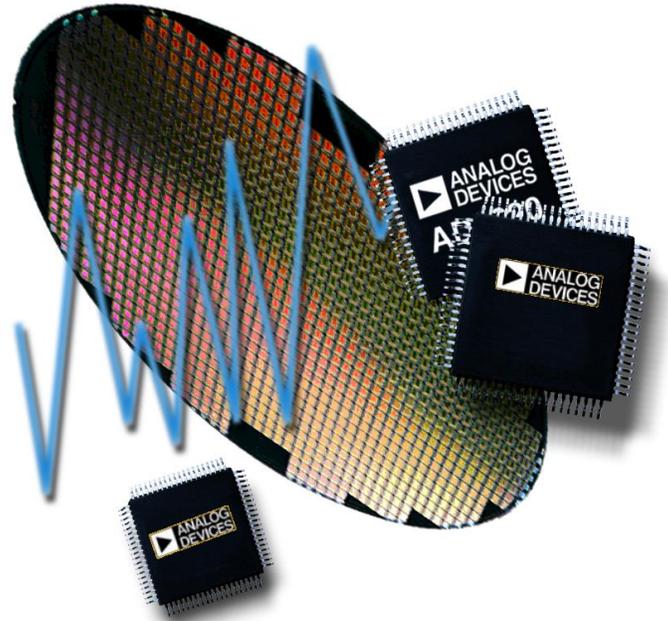
## Appendix A - Affected ADI Models:

### Added Parts On This Revision - Product Family / Model Number (12)

LT8648S / LT8648SEV#PBF	LT8648S / LT8648SEV#TRPBF	LT8648S / LT8648SEV#WPBF	LT8648S / LT8648SEV#WTRPBF	LT8648S / LT8648SHV#PBF
LT8648S / LT8648SHV#TRPBF	LT8648S / LT8648SHV#WPBF	LT8648S / LT8648SHV#WTRPBF	LT8648S / LT8648SJ#PBF	LT8648S / LT8648SJ#TRPBF
LT8648S / LT8648SJ#WPBF	LT8648S / LT8648SJ#WTRPBF			

**Appendix B - Revision History:**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	06-Mar-2024	08-Jun-2024	Initial Release



# ***Reliability Report***

**Report Title:** LT8648S Assembly Process Change  
Automotive Grade 0 Qualification

**Report Number:** 20710

**Revision:** A

**Date:** 4 December 2023

## Summary

This report documents the successful completion of the reliability qualification requirements for the release of the LT8648S product in a 36-LGA package. LT8648S is a 42V,15A synchronous step-down silent switcher 2. Following changes were made, Die thickness from 450um to 200um and SMD attach material from SnSb5 to SAC305.

## AECQ100 Qualification Test Methods and Summary

AEC Test Group	AEC Stress Test Name	Abbreviation	AEC Test #	Reference
<b>Group A</b> ACCELERATED ENVIRONMENT STRESS TESTS	Preconditioning	PC	A1	Table 2 and Table 4
	Temperature Humidity Bias or Biased-HAST	THB or HAST	A2	
	Autoclave or Unbiased HAST or Temperature Humidity (without Bias)	AC, UHST, or TH	A3	
	Temperature Cycle	TC	A4	
	Power Temperature Cycling	PTC	A5	
	High Temperature Storage Life	HTSL	A6	
<b>Group B</b> ACCELERATED LIFETIME SIMULATION TESTS	High Temperature Operating Life	HTOL	B1	Table 2 and Table 4
	Early Life Failure Rate	ELFR	B2	
	NVM Endurance, Data Retention, and Operational Life	EDR	B3	
<b>Group C</b> PACKAGE ASSEMBLY INTEGRITY TESTS	Wire Bond Shear	WBS	C1	<ul style="list-style-type: none"> <li>C1, C2 are only applicable for wire bond package.</li> <li>C5 is only applicable for BGA package.</li> <li>C3, C4 and C6 are qualified and controlled with inline monitors and may be viewed on site at Analog Devices.</li> </ul>
	Wire Bond Pull Strength	WBP	C2	
	Solderability	SD	C3	
	Physical Dimensions	PD	C4	
	Solder Ball Shear	SBS	C5	
	Lead Integrity	LI	C6	
<b>Group D</b> DIE FABRICATION RELIABILITY TESTS	Electromigration	EM	D1	Die Fabrication Reliability data may be viewed on-site at Analog Devices.
	Time Dependent Dielectric Breakdown	TDDB	D2	
	Hot Carrier Injection	HCI	D3	
	Negative Bias Temperature Instability	BTI	D4	
	Stress Migration	SM	D5	
<b>Group E</b> ELECTRICAL VERIFICATION TESTS	Pre- and Post-Stress Electrical Test	TEST	E1	Table 5 and Table 6
	Electrostatic Discharge Human Body Model	HBM	E2	
	Electrostatic Discharge Charged Device Model	CDM	E3	
	Latch-Up	LU	E4	<ul style="list-style-type: none"> <li>For Tests E5, E6 and E7, ADI New Product Yield Analysis Testing Guidelines meet AEC Q100 requirements.</li> <li>Results for Tests E7-E11 are available as applicable on a case by case basis.</li> <li>Test E12 results may be viewed on-site at Analog Devices</li> </ul>
	Electrical Distributions	ED	E5	
	Fault Grading	FG	E6	
	Characterization	CHAR	E7	
	Electromagnetic Compatibility	EMC	E9	
	Short Circuit Characterization	SC	E10	
	Soft Error Rate	SER	E11	
	Lead (Pb) Free	LF	E12	
	<b>Group F</b> DEFECT SCREENING TESTS	Process Average Test	PAT	
Statistical Bin/Yield Analysis		SBA	F2	
<b>Group G</b> CAVITY PACKAGE INTEGRITY TESTS	Mechanical Shock	MS	G1	<Applicable only for Cavity Packages>
	Variable Frequency Vibration	VFV	G2	
	Constant Acceleration	CA	G3	
	Gross/Fine Leak	GFL	G4	
	Package Drop	DROP	G5	
	Lid Torque	LT	G6	
	Die Shear	DS	G7	
	Internal Water Vapor	IWV	G8	

**Die/Fab Product Characteristics**
**Table 1: Die/Fab Product Characteristics- 0.35µm DMOS**

Product Characteristics	Product(s) to be qualified	Product(s) used for Substitution Data			
		LT8390	LT8638S	LT8650S/SP/SPA	LT8686S
Generic/Root Part #	LT8648S	LT8390	LT8638S	LT8650S/SP/SPA	LT8686S
Die Id	8648	8390	8638S	8650	8686
Die Size (mm)	6.20 x 2.70	1.52 x 2.44	4.02 x 2.59	1.75 x 3.88	3.20 x 1.75
Wafer Fabrication Site	Vanguard	Vanguard	Vanguard	Vanguard	Vanguard Fab1
Wafer Fabrication Process	0.35µm DMOS	0.35µm DMOS	0.35µm DMOS	0.35µm DMOS	0.35µm DMOS
Die Substrate	Si	Si	Si	Si	Si
Metallization / # Layers	AlCu/3	AlCu/2	AlCu/3	AlCu/3	AlCu/3
Polyimide	No	No	No	No	No
Passivation	undoped-oxide/SiN	undoped-oxide/SiN	undoped-oxide/SiN	undoped-oxide/SiN	undoped-oxide/SiN

**Die/Fab Test Results**
**Table 2: Die/Fab Test Results - 0.35µm DMOS at Vanguard**

Test Name	AEC #	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS	eTest Temp
Early Life Failure Rate (ELFR)	B2	AEC-Q100-008	Ta=150°C, 48 Hours	LT8390	Q16133.1ELFR	0/800	RH
				LT8648S	EO9353.ELFR	0/800	RH
				LT8650SP	Q17503.1ELFR	0/800	RH
High Temperature Operating Life (HTOL)	B1	JESD22-A108	Ta=150°C, Biased, 2,000 Hours	LT8650SPA	Q20156.1HTOL	0/77	RCH
			Ta=150°C, Biased, 1,000 Hours	LT8650S	Q20616.3HTOL	0/77	RHC
				LT8638S	Q20120.4HTOL	0/77	RHC
				LT8648S	EO9459L.HTOL	0/77	RHC
					Q20710.2HTOL	0/77	RHC
LT8686S	Q20395.1HTOL	0/77	RHC				
High Temperature Storage Life (HTSL)	A6	JESD22-A103	150°C, 2,000 Hours	LT8638S	Q20120.2HTS	0/50	RH
				LT8648S	Q20710.2HTS	0/50	RH
				LT8650S	Q20616.3HTS	0/50	RH
Highly Accelerated Temperature and Humidity Stress Test (HAST) <sup>1</sup>	A2	JESD22-A110	110°C 85%RH 17.7 psia, Biased, 264 Hours	LT8638S	Q20120.4HAST	0/77	RH
			130C 85%RH 33.3 psia, Biased, 96 Hours	LT8638S	Q20120.3HAST	0/77	RH
				LT8650S	Q20616.2HAST	0/77	RH
					Q20616.3HAST	0/77	RH
			Q20616.4HAST	0/77	RH		
			130C 85%RH 33.3 psia, Biased, 192 Hours	LT8648S	Q20710.1HAST	0/77	RH
Q20710.2HAST	0/77	RH					

<sup>1</sup> These samples were subjected to preconditioning at MSL 3 with 3x reflow peak temp of 260°C prior to the start of the stress test.

**Package/Assembly Product Characteristics**

**Table 3: Package/Assembly Product Characteristics - 36-LGA at ASE**

Product Characteristics	Product(s) to be qualified	Product(s) used for Substitution Data			
Generic/Root Part #	LT8648S	LT8686S	LT8350	LT8638S	LT8650S
Package	36-LGA	32-LGA	28-LGA	28-LGA	32-LGA
Body Size (mm)	7.00 x 4.00 x 0.94	5.00 x 5.00 x 0.95	6.00 x 4.00 x 0.94	5.00x4.00x0.94	6.00 x 4.00 x 0.94
Assembly Location	ASE	ASE	ASE	ASE	ASE
MSL/Peak Reflow Temperature(°C)	3 / 260°C	3 / 260°C	3 / 260°C	3 / 260°C	3 / 260°C
Mold Compound	Sumitomo G311E	Sumitomo G311E	Sumitomo G311E	Sumitomo G311E	Sumitomo G311E
Substrate Material	BT Resin	BT Resin	BT Resin	BT Resin	BT Resin
Lead Finish	Au	Au	Au	Au	Au

**Package/Assembly Test Results**
**Table 4: Package/Assembly Test Results - LGA at ASE**

Test Name	AEC #	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS	eTest Temp
High Temperature Storage Life (HTSL)	A6	JESD22-A103	150°C, 2,000 Hours	LT8638S	Q20120.2HTS	0/45	RH
				LT8648S	Q20710.2HTS	0/45	RH
				LT8650S	Q20616.3HTS	0/77	RH
Highly Accelerated Temperature and Humidity Stress Test (HAST) <sup>1</sup>	A2	JESD22-A110	110°C 85%RH 17.7 psia, Biased, 264 Hours	LT8638S	Q20120.4HAST	0/77	RH
				LT8650S	Q20151.1HAST	0/77	RH
				LT8638S	Q20120.3HAST	0/77	RH
			130°C 85%RH 33.3 psia, Biased, 96 Hours	LT8650S	Q20616.2HAST	0/77	RH
					Q20616.3HAST	0/77	RH
					Q20616.4HAST	0/77	RH
			LT8686S	Q20395.1HAST	0/77	RH	
			130°C 85%RH 33.3 psia, Biased, 192 Hours	LT8648S	Q20710.1HAST	0/77	RH
					Q20710.2HAST	0/77	RH
Solder Heat Resistance (SHR)	A1	J-STD-020	MSL-3	LT8648S	Q20710.1SHR	0/77	R
					Q20710.2SHR	0/77	R
Temperature Cycling (TC) <sup>1</sup>	A4	JESD22-A104	-65°C/+150°C, 2,000 Cycles	LT8350	Q20636.1.TC1_POR	0/77	RH
					Q20636.1.TC2_TR	0/77	RH
				LT8648S	Q20710.1TC	0/77	RH
					Q20710.2TC	0/77	RH
				LT8650S	Q20616.1TC	0/77	RH
					Q20616.2TC	0/77	RH
					Q20616.3TC	0/77	RH
					Q20616.4TC	0/77	RH
				LT8638S	Q20120.1TC	0/77	RH
					Q20120.2TC	0/77	RH
Q20120.3TC	0/77	RH					
Unbiased HAST (UHST) <sup>1</sup>	A3	JESD22-A118	130°C 85%RH 33.3 psia, 96 Hours	LT8650S	Q20616.1UHAST	0/77	R
					Q20616.2UHAST	0/77	R
					Q20616.3UHAST	0/77	R
				LT8686S	Q20395.1UHAST	0/77	R

Test Name	AEC #	Spec	Conditions	Generic/Root Part #	Lot #	Fail/SS	eTest Temp
Unbiased HAST (UHST) <sup>1</sup>	A3	JESD22-	130°C 85%RH 33.3 psia, 96 Hours	LT8648S	Q20710.1UHAST_A	0/77	R
		A118			Q20710.2UHAST	0/77	R

<sup>1</sup> These samples were subjected to preconditioning at MSL 3 with 3x reflow peak temp of 260°C prior to the start of the stress test.

## ESD and Latch-Up Test Results

**Table 5: ESD Test Results**

ESD Model	Generic/Root Part#	Package	ESD Test Spec	RC Network	Highest Pass Level	Class	eTest Temp
FICDM	LT8648S	36-LGA	JS-002	1Ω, Cpkg	±1000V	C3	RH
HBM	LT8648S	36-LGA	ESDA/JEDEC JS-001-2011	1.5kΩ, 100pF	±3000V	2	RH

**Table 6: Latch Up Test Result**

LU Test Spec	Generic/Root Part #	Passing Current	Passing Over-Voltage	Temperature (T <sub>A</sub> )	Class	eTest Temp
JESD78	LT8648S	+150mA, -150mA	+6V/+28V/+48V	150°C	II	RH

## Approvals

Reliability Engineer: Devraj Karthikeyan